

## **PLASMA PROCESS FOR REMOVING POLYMER AND RESIDUES FROM SUBSTRATES**

### **ABSTRACT**

A process for removing polymers formed during etching and etch residues from a semiconductor substrate by exposing the substrate to plasmas of neutral chemistry. The plasma generates atomic hydrogen species and atomic oxygen species in about equal amounts that react with and remove the polymers and etch residues from the substrate.

The process is especially suitable for use with semiconductor substrates comprising low k dielectric materials and/ or copper interconnects.